

A CLAMPING ASSEMBLY

Abstract

A clamping assembly for clamping a lead frame with pre-attached semiconductor device, comprising of: a first member, to hold the lead frame, said first member having a surface profile in contact with a surface profile of the semiconductor device, a second member for allowing the mounting of the first member thereon, an attachment means to secure the first member onto the second member, wherein the attachment means is adjustable to conform the surface profile of the first member to the surface profile of the lead frame.

Figure 2